

V3.0.0

MMIC Single Channel Series Fixed Attenuator DC-50/60/65GHz

Features

· Ultra broadband single channel attenuator

• Frequency Range: DC-50 / 60 / 65GHz

• Attenuation 0, 1, 2...10,15, 20, 30dB value

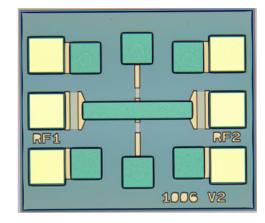
• Power Handling: 27dBm

• 50Ω Input and Output Impedance

• Return Loss: 15dB

• Chip Size: 0.656 x 0.566 x 0.1mm

· RoHS & REACH Compliant



Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

 $TA = +25^{\circ}C$

Part Number	Туре	Frequency (GHz)	Attenuation (dB)	Power Handling (dBm)	Attenuation Flatness (dB)	Return Loss
MFA1001	Fixed Attenuator	DC-50	0	27	±0.3	15
MFA1002	Fixed Attenuator	DC-65	1	27	±0.5	10
MFA1003	Fixed Attenuator	DC-60	2	27	±0.3	10
MFA1004	Fixed Attenuator	DC-60	3	27	±0.3	10
MFA1005	Fixed Attenuator	DC-65	4	27	±0.3	10
MFA1006	Fixed Attenuator	DC-65	5	27	±0.3	15
MFA1007	Fixed Attenuator	DC-50	6	27	±0.3	15
MFA1008	Fixed Attenuator	DC-50	7	27	±0.5	15
MFA1009	Fixed Attenuator	DC-50	8	27	±0.5	15
MFA1010	Fixed Attenuator	DC-60	9	27	±0.5	15
MFA1011	Fixed Attenuator	DC-65	10	27	±1.0	18
MFA1012	Fixed Attenuator	DC-65	15	27	±1.0	18
MFA1013	Fixed Attenuator	DC-65	20	27	±0.4	12
MFA1014	Fixed Attenuator	DC-65	30	27	±1.5	10

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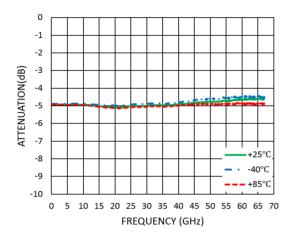
Sales: sales@millermmic.com



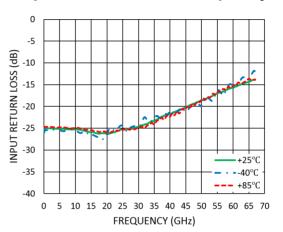
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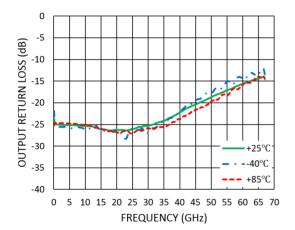
Attenuation vs. Frequency



Input Return Loss vs. Frequency



Output Return Loss vs. Frequency



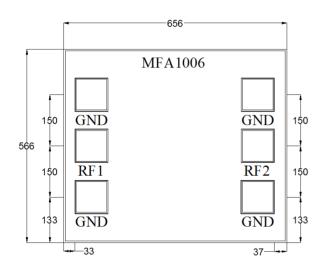


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Outline Drawing:

All Dimensions in µm



No	Function	Description
1	RF 1	RF Signal Input. This pad is ac-coupled and matched to 50 Ω.
2	RF 2	RF Signal Output. This pad is ac-coupled and matched to 50 Ω.
3	Die Bottom	Die bottom must be connected to RF/ DC ground.

Notes:

1. Die thickness: 100µm

Typical bond pad is 90*90 μm²
Bond pad metalization: Gold

4. Backside metalization: Gold

5. No connection required for unlabeled bond pads

Maximum Ratings:

1. Maximum input power: +30dBm

2. Operating temperature: -55°C to +120°C

3. Storage temperature: -65°C to +150°C

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